Small Signal MOSFET

Complementary 20 V, 540 mA / -430 mA, with ESD protection, SOT-563 package.

Features

- Leading Trench Technology for Low RDS(on) Performance
- High Efficiency System Performance
- Low Threshold Voltage
- ESD Protected Gate
- Small Footprint 1.6 x 1.6 mm
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- DC-DC Conversion Circuits
- Load/Power Switching with Level Shift
- Single or Dual Cell Li-Ion Battery Operated Systems
- High Speed Circuits
- Cell Phones, MP3s, Digital Cameras, and PDAs

MAXIMUM RATINGS (T_J = 25°C unless otherwise specified)

Para	Symbol	Value	Unit			
Drain-to-Source Voltag	V_{DSS}	20	V			
Gate-to-Source Voltag	je		V_{GS}	±6	V	
N-Channel Continu-	Steady	$T_A = 25^{\circ}C$		540	mA	
ous Drain Current (Note 1)	State	$T_A = 85^{\circ}C$		390		
	t ≤ 5 s	$T_A = 25^{\circ}C$	1_	570		
P-Channel Continu-	Steady	$T_A = 25^{\circ}C$	l _D	-430		
ous Drain Current (Note 1)	State	$T_A = 85^{\circ}C$		-310		
	$t \le 5 \text{ s}$ $T_A = 25^{\circ}\text{C}$			-455		
Power Dissipation	Steady	T _A = 25°C	P _D	250	mW	
(Note 1)	State					
	t ≤ 5 s			280		
Pulsed Drain Current	N-Channel	+ 10	I _{DM}	1500	mA	
	P -Channel $t_p = 10 \mu$				ША	
Operating Junction and	T _J ,	-55 to	°C			
	T _{STG}	150				
Source Current (Body I	I _S	350	mA			
Lead Temperature for S (1/8" from case for 1	TL	260	°C			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface-mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq [1 oz] including traces).

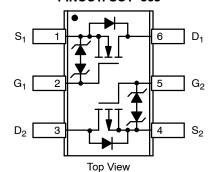


ON Semiconductor®

http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max (Note 1)
N OL I	0.4 Ω @ 4.5 V	
N-Channel 20 V	0.5 Ω @ 2.5 V	540 mA
	0.7 Ω @ 1.8 V	
	0.5 Ω @ -4.5 V	
P-Channel -20 V	0.6 Ω @ -2.5 V	–430 mA
	1.0 Ω @ -1.8 V	

PINOUT: SOT-563





MARKING DIAGRAM

CASE 463A

TW = Specific Device Code

= Date Code М = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]			
NTZD3155CT1G	SOT-563	4000 / Tape & Reel			
NTZD3155CT1H	(Pb-Free)	4000 / Tape & Reel			
NTZD3155CT2G	SOT-563	4000 / Tape & Reel			
NTZD3155CT2H	(Pb-Free)	4000 / Tape & nee			
NTZD3155CT5G	SOT-563	8000 / Tape & Reel			
NTZD3155CT5H	(Pb-Free)	1 0000 / Tape & Tieer			

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Thermal Resistance Ratings

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 2)	$R_{ hetaJA}$	500	°C/W
Junction-to-Ambient – t = 5 s (Note 2)		447	

^{2.} Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).

ELECTRICAL CHARACTERISTICS (T₁ = 25°C unless otherwise specified)

Parameter	Symbol	N/P	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•	•		•	•	•	•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	N	V _{GS} = 0 V	I _D = 250 μA	20			V
		Р	1	I _D = -250 μA	-20			
Drain-to-Source Breakdown Voltage Temperature Coefficient	V(BR)DSS/TJ			•		18		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	N	V _{GS} = 0 V, V _{DS} = 16 V	T _J = 25°C			1.0	μΑ
		Р	V _{GS} = 0 V, V _{DS} = -16 V				-1.0	
		N	V _{GS} = 0 V, V _{DS} = 16 V	T _J = 125°C			2.0	μΑ
		Р	V _{GS} = 0 V, V _{DS} = - 16V				-5.0	
Gate-to-Source Leakage Current	I _{GSS}	Р	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$				±2.0	μΑ
		N					±5.0	
ON CHARACTERISTICS (Note 3)								
Gate Threshold Voltage	V _{GS(TH)}	N	$V_{GS} = V_{DS}$	I _D = 250 μA	0.45		1.0	V
		Р		I _D = -250 μA	-0.45		-1.0	
Gate Threshold Temperature Coefficient	V _{GS(TH)} /T _J					-1.9		-mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	N	V_{GS} = 4.5 V, I_{D} = 540 mA V_{GS} = -4.5 V, I_{D} = -430 mA V_{GS} = 2.5 V, I_{D} = 500 mA V_{GS} = -2.5 V, I_{D} = -300 mA			0.4	0.55	
		Р				0.5	0.9	Ω
		N				0.5	0.7	
		Р				0.6	1.2	
		N	V _{GS} = 1.8 V, I _D = 350 mA			0.7	0.9	
		Р	$V_{GS} = -1.8V$, $I_D = -150 \text{ mA}$			1.0	2.0	
Forward Transconductance	9FS	N V _{DS} = 10 V, I _D = 540 mA		540 mA		1.0		S
		Р	$V_{DS} = -10 \text{ V}, I_{D} = -$	-430 mA		1.0		8
CHARGES, CAPACITANCES AND GA	ATE RESISTAN	ICE						
Input Capacitance	C _{ISS}					80	150	
Output Capacitance	C _{OSS}	N	f = 1 MHz, V _{GS} = 0 V V _{DS} = 16 V			13	25	- -
Reverse Transfer Capacitance	C _{RSS}	1				10	20	
Input Capacitance	C _{ISS}					105	175	pF
Output Capacitance	C _{OSS}	Р	$f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$ $V_{DS} = -16 \text{ V}$			15	30	7
Reverse Transfer Capacitance	C _{RSS}	1				10	20	

^{3.} Pulse Test: pulse width $\leq\!300~\mu\text{s},$ duty cycle $\leq\!2\%$

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	N/P	Test Conditi	on	Min	Тур	Max	Unit	
CHARGES, CAPACITANCES AND GATE RESISTANCE									
Total Gate Charge	Q _{G(TOT)}					1.5	2.5		
Threshold Gate Charge	Q _{G(TH)}	N				0.1			
Gate-to-Source Charge	Q _{GS}	1	$V_{GS} = 4.5 \text{ V}, V_{DS} = -10 \text{ V}; I_D = 540 \text{ mA}$		0.2				
Gate-to-Drain Charge	Q_{GD}	1				0.35		0	
Total Gate Charge	Q _{G(TOT)}					1.7	2.5	nC	
Threshold Gate Charge	Q _{G(TH)}	P	V _{GS} = -4.5 V, V _{DS} = 10 V	; I _D = -380 mA		0.1			
Gate-to-Source Charge	Q _{GS}] [, , , , , , , , , , , , , , , , , , , ,		0.3			
Gate-to-Drain Charge	Q_{GD}	1				0.4			
SWITCHING CHARACTERISTIC	CS (V _{GS} = V) (Not	e 4)							
Turn-On Delay Time	t _{d(ON)}	N	V_{GS} = 4.5 V, V_{DD} = -10 V, I_{D} = 540 mA, R_{G} = 10 Ω			6.0			
Rise Time	t _r	1				4.0			
Turn-Off Delay Time	t _{d(OFF)}	1				16			
Fall Time	t _f	1				8.0			
Turn-On Delay Time	t _{d(ON)}	Р				10		ns	
Rise Time	t _r	1	V _{GS} = -4.5 V, V _{DD} = 10 V,	, I _D = -215 mA,		12		1	
Turn-Off Delay Time	t _{d(OFF)}	1	$V_{GS} = -4.5 \text{ V}, V_{DD} = 10 \text{ V}, R_{G} = 10 \Omega$			35			
Fall Time	t _f	1				19			
Drain-Source Diode Character	istics	-							
Forward Diode Voltage	V _{SD}	N	I _S = 350 mA			0.7	1.2		
		Р	$V_{GS} = 0 \text{ V, } T_{J} = 25^{\circ}\text{C}$	$I_{S} = -350 \text{ mA}$		-0.8	-1.2	V	
Reverse Recovery Time	t _{RR}	N	V _{GS} = 0 V, I _S = 350 mA			6.5			
P dIS/dt = 100 A/μs		$I_S = -350 \text{ mA}$		13		ns			

^{4.} Switching characteristics are independent of operating junction temperatures

N-CHANNEL TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

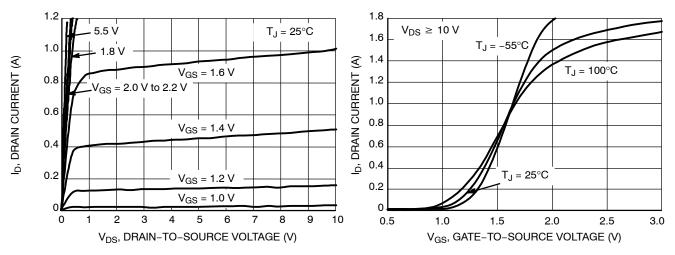


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

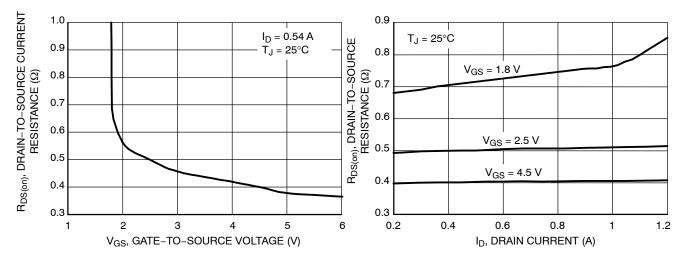


Figure 3. On-Resistance versus Gate-to-Source Voltage

Figure 4. On-Resistance versus Drain Current and Gate Voltage

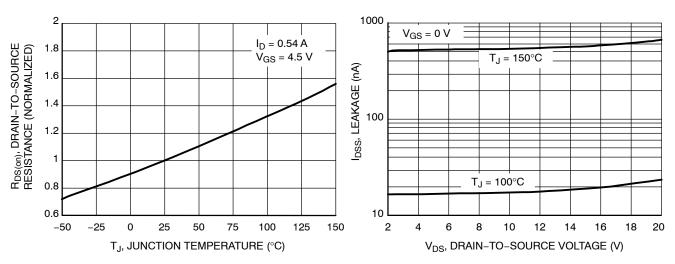


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current versus Voltage

N-CHANNEL TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

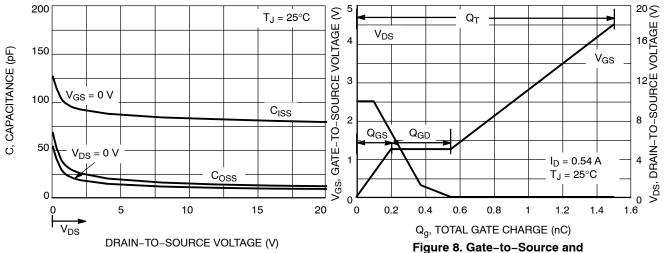


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

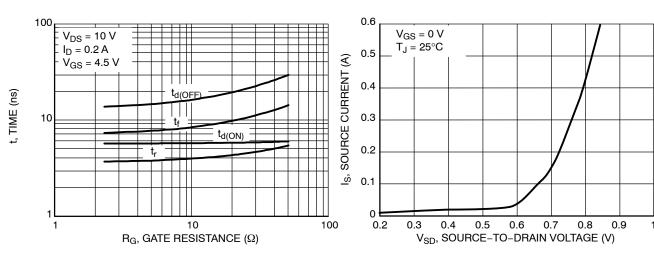


Figure 9. Resistive Switching Time Variation versus Gate Resistance

Figure 10. Diode Forward Voltage versus Current

P-CHANNEL TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

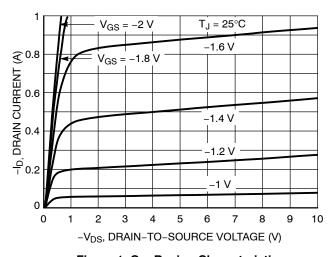


Figure 1. On-Region Characteristics

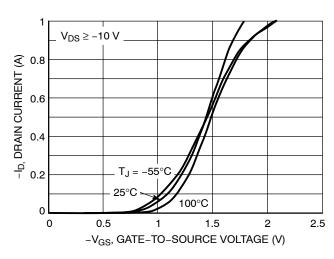


Figure 2. Transfer Characteristics

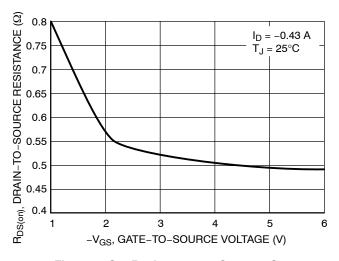


Figure 3. On-Resistance vs. Gate-to-Source Voltage

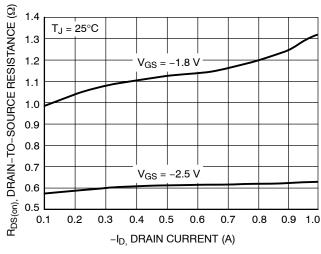


Figure 4. On–Resistance vs. Drain Current and Gate Voltage

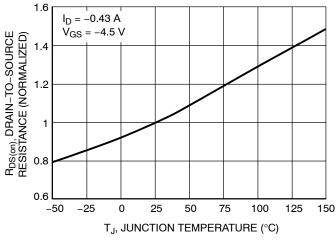


Figure 5. On–Resistance Variation with Temperature

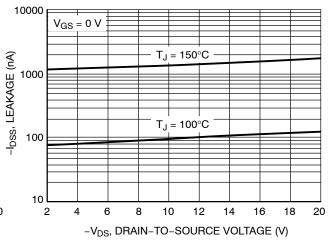


Figure 6. Drain-to-Source Leakage Current vs. Voltage

P-CHANNEL TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)

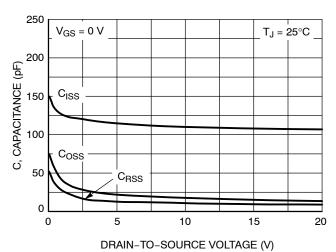


Figure 7. Capacitance Variation

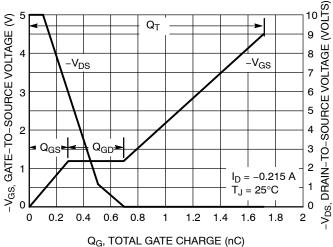


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

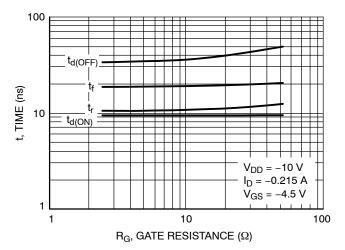


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

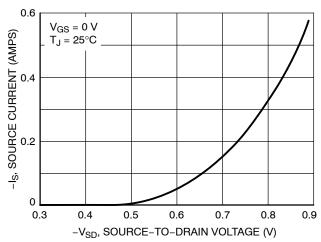
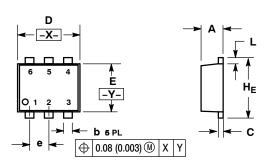


Figure 10. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SOT-563, 6 LEAD CASE 463A ISSUE F

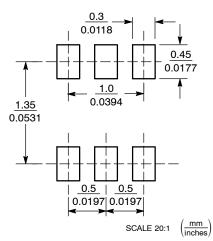


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES				
DIM	MIN	NOM	MAX	MIN	NOM	MAX		
Α	0.50	0.55	0.60	0.020	0.021	0.023		
b	0.17	0.22	0.27	0.007	0.009	0.011		
С	0.08	0.12	0.18	0.003	0.005	0.007		
D	1.50	1.60	1.70	0.059	0.062	0.066		
Е	1.10	1.20	1.30	0.043	0.047	0.051		
е		0.5 BSC)	0.02 BSC				
Г	0.10	0.20	0.30	0.004	0.008	0.012		
HE	1.50	1.60	1.70	0.059	0.062	0.066		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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